

# WAFER PREPARATION AND IODINE-ETHANOL PASSIVATION PROCEDURE FOR REPRODUCIBLE MINORITY-CARRIER LIFETIME MEASUREMENT

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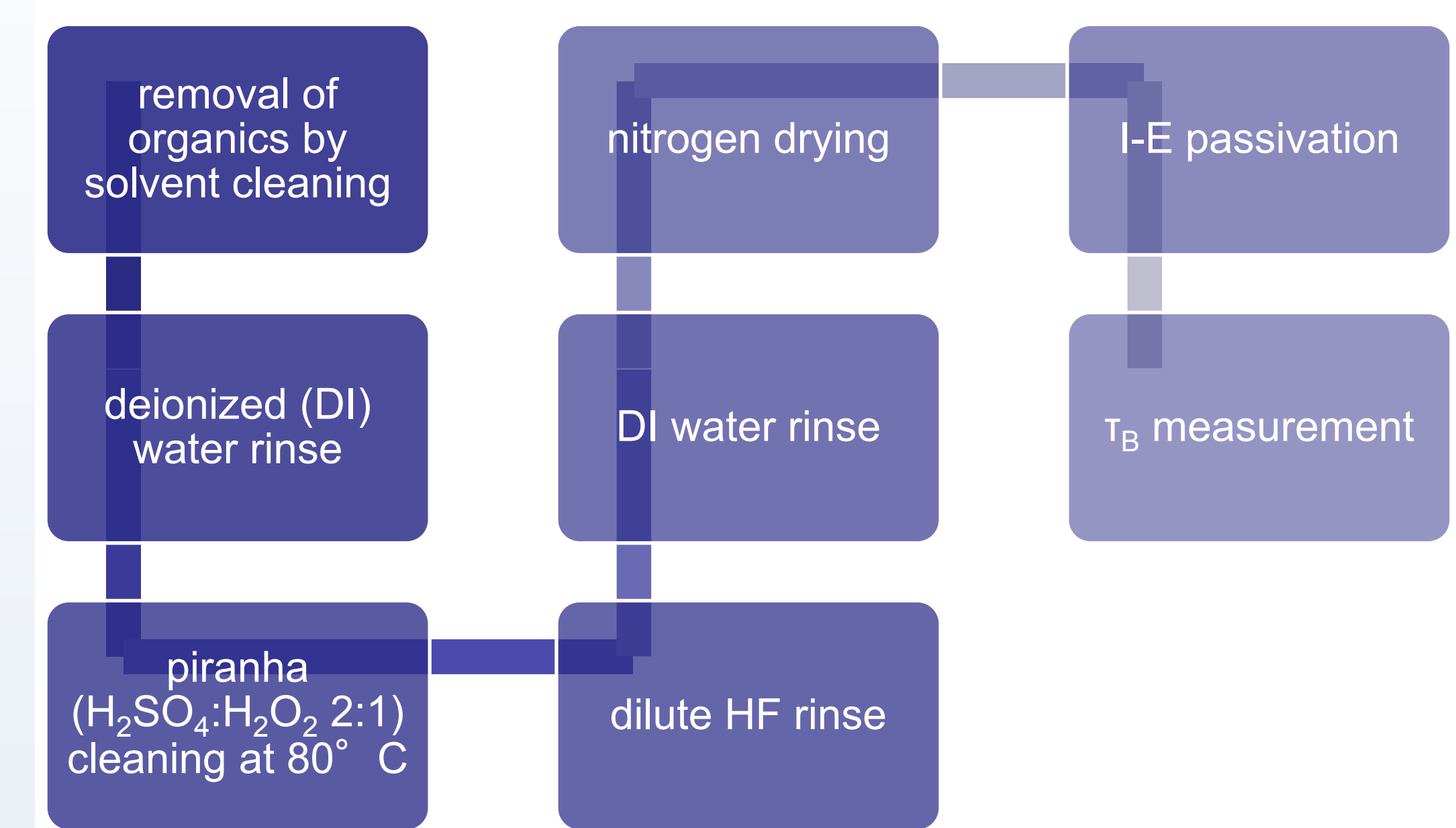
## INTRODUCTION

- Measurement of the bulk minority-carrier lifetime ( $\tau_b$ ) by optical methods, such as photocurrent decay or quasi-steady-state photoconductance (QSSPC), is strongly influenced by surface recombination.
- Several techniques are known to lower the effective surface recombination velocity, including the following: use of oxidation, floating N/P junction, SiN:H layer, HF immersion, and use of iodine in ethanol or methanol (I-E solution).
- Using I-E appears to be very simple and does not require any high-temperature treatment such as oxidation, diffusion, or nitridation processes, which can change  $\tau_b$ .
- However, this is not a preferred procedure within the photovoltaic community because it is difficult to obtain same  $\tau_b$  values reproducibly, particularly when the wafer lifetime is long.

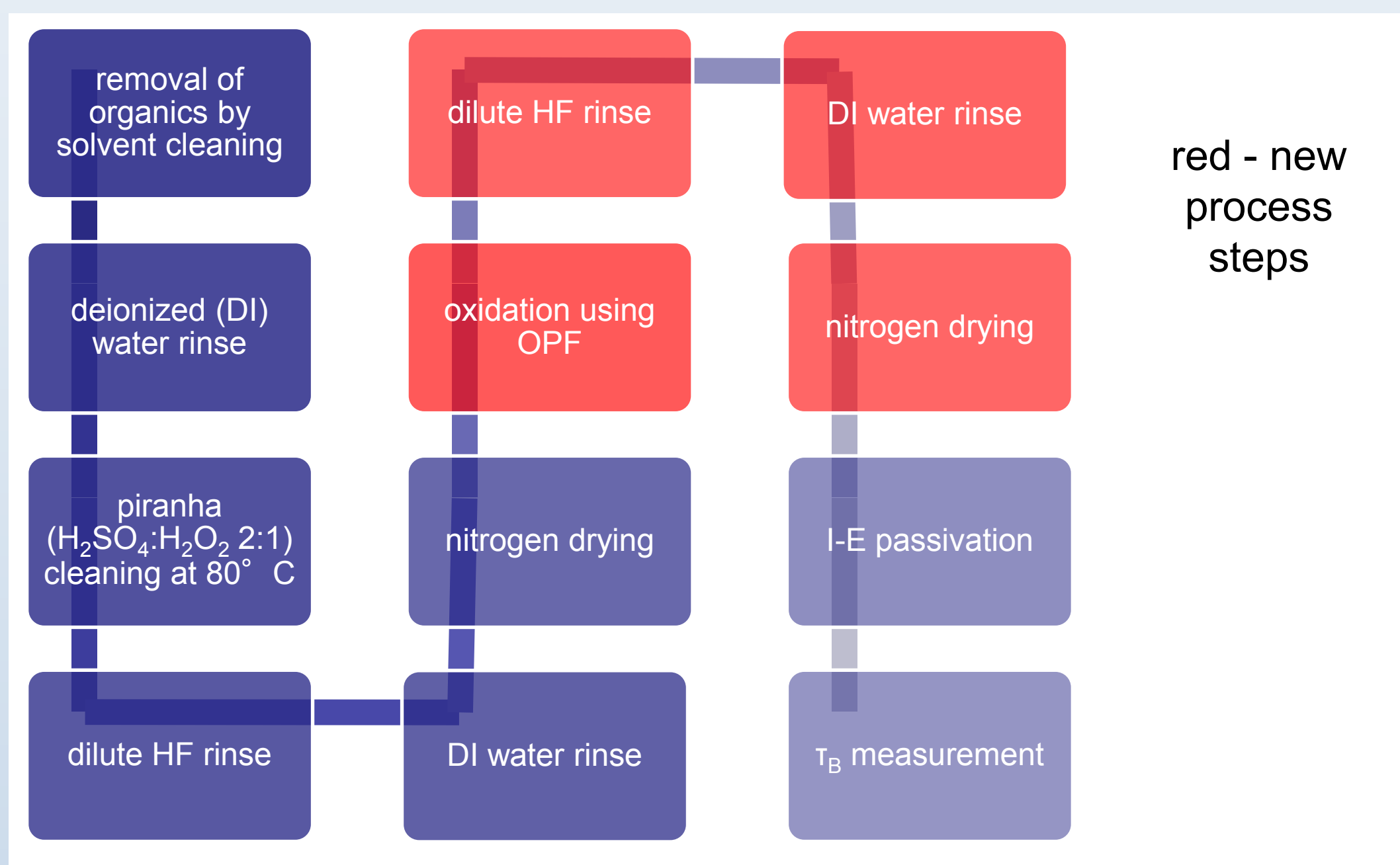
## OBJECTIVES FOR STUDYING LIFETIME MEASUREMENTS AND I-E PASSIVATION

- Investigate various reasons why lifetime measurements may be irreproducible using I-E solution passivation.
- Study the influence of the strength of iodine in the ethanol solution, wafer-cleaning procedures, influence of the wafer container during lifetime measurements, and the stability of I-E.
- Compare lifetimes of wafers (having different  $\tau_b$ ) by various techniques such as QSSPC and transient photoconductive decay using short laser pulses of different light intensity;
- Make minority-carrier diffusion length (L) measurements by a surface photovoltage technique, and to use  $\tau_b$  and L data to determine diffusivity (D) values for various impurity and defect concentrations, using the relationship  $L^2 = D \cdot \tau_b$ .

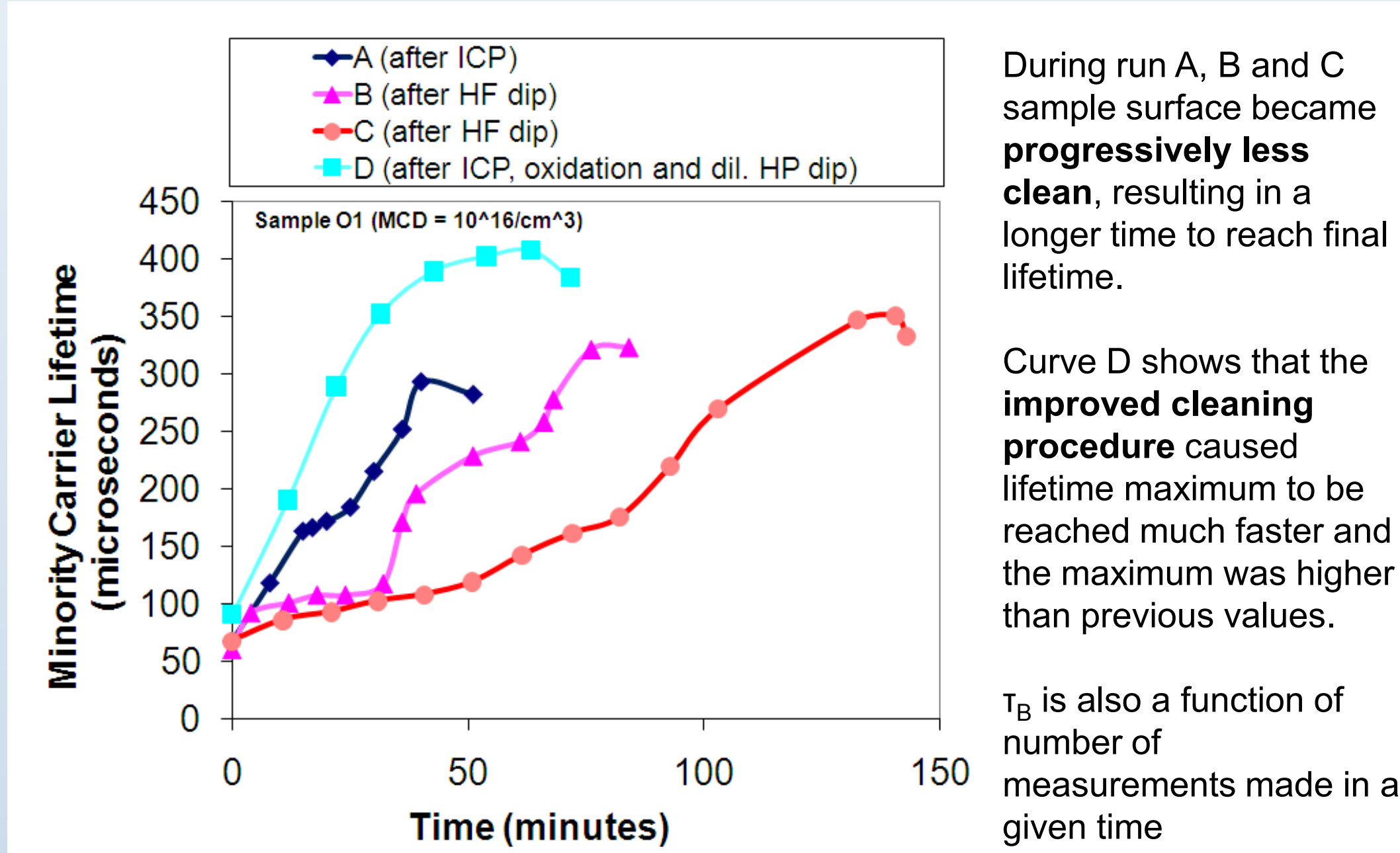
## INITIAL CLEANING PROCEDURE (ICP)



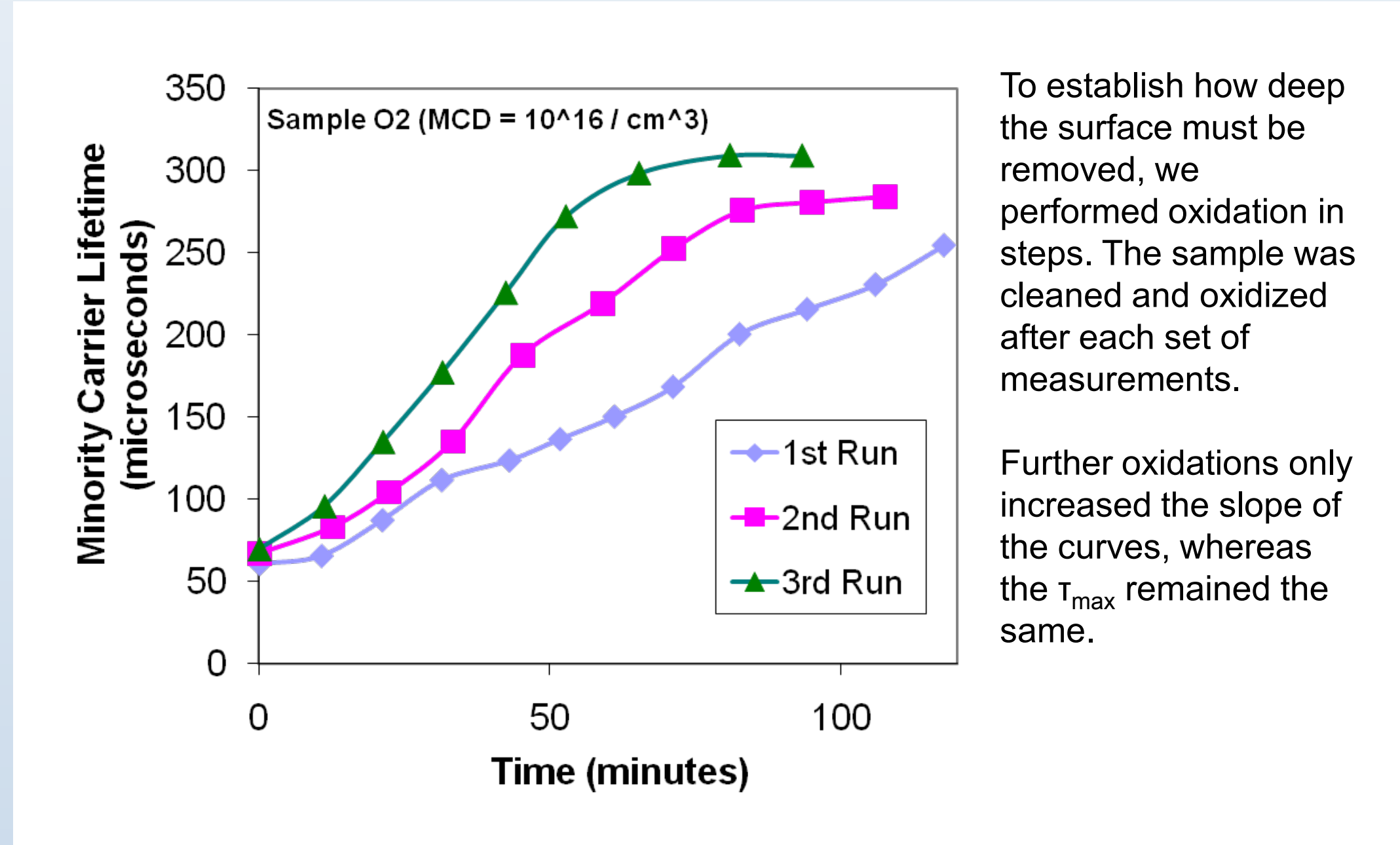
## IMPROVED CLEANING PROCEDURE



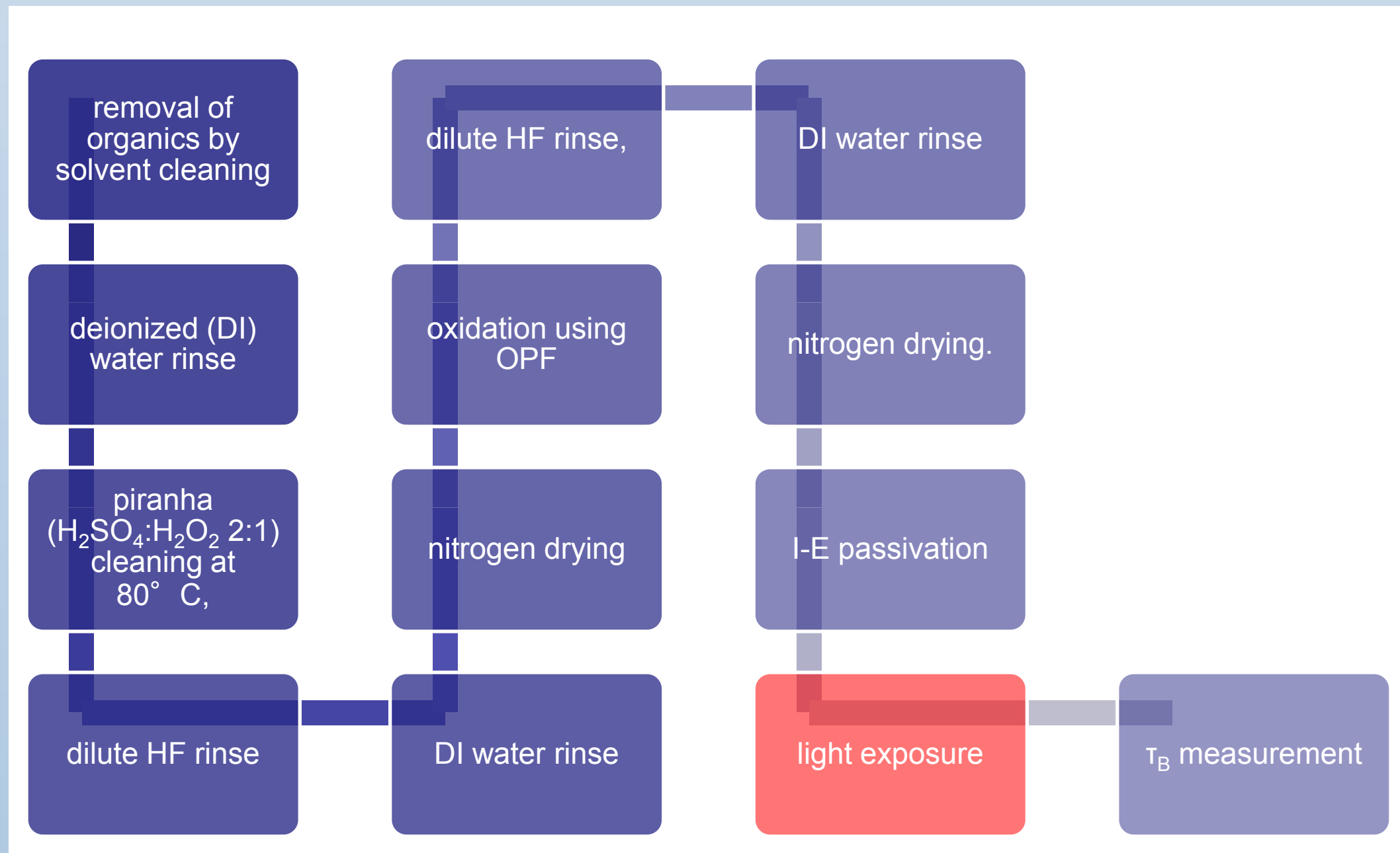
## COMPARISON OF CLEANING PROCEDURES



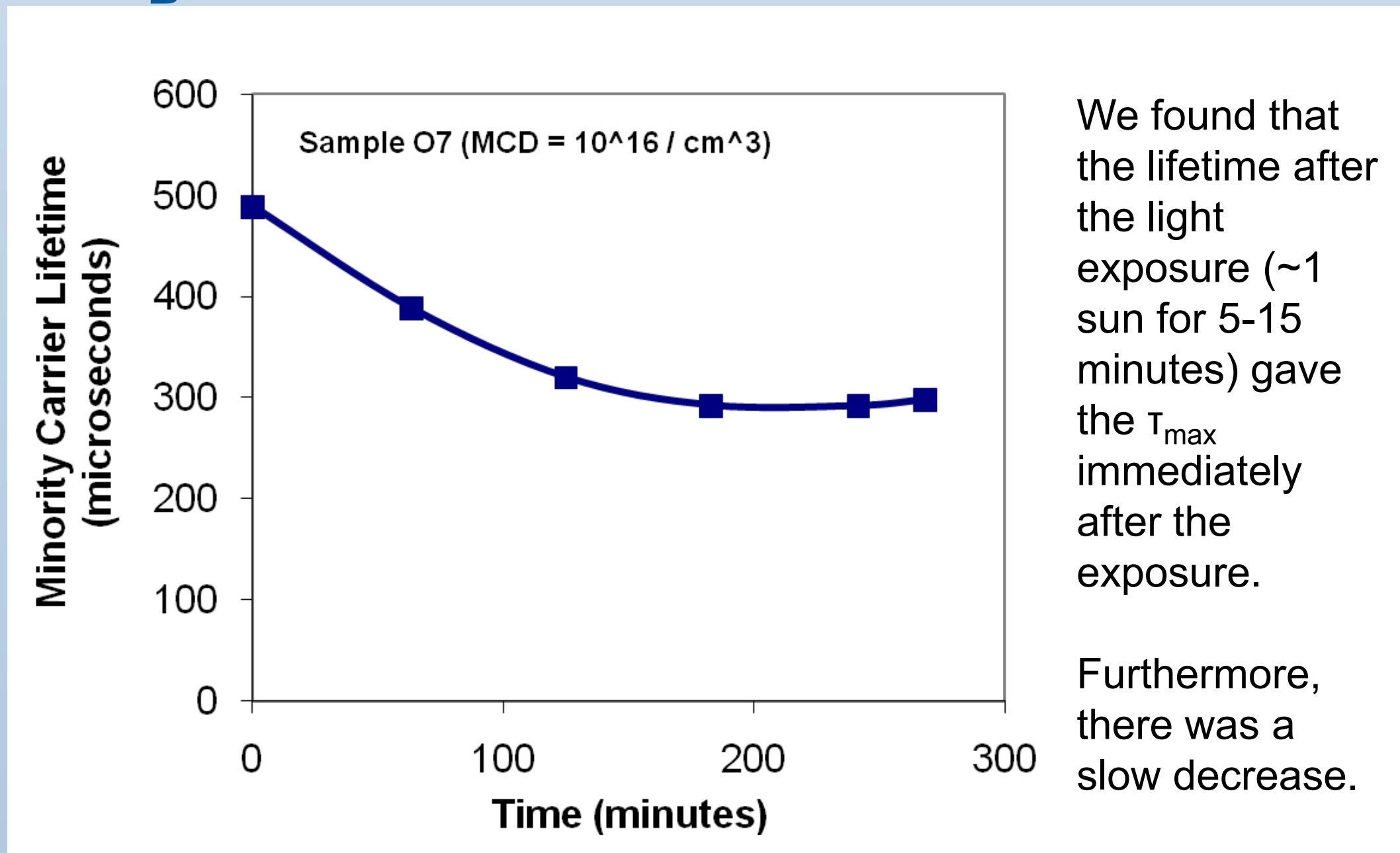
## RESULTS FOR SEQUENTIAL CLEANING



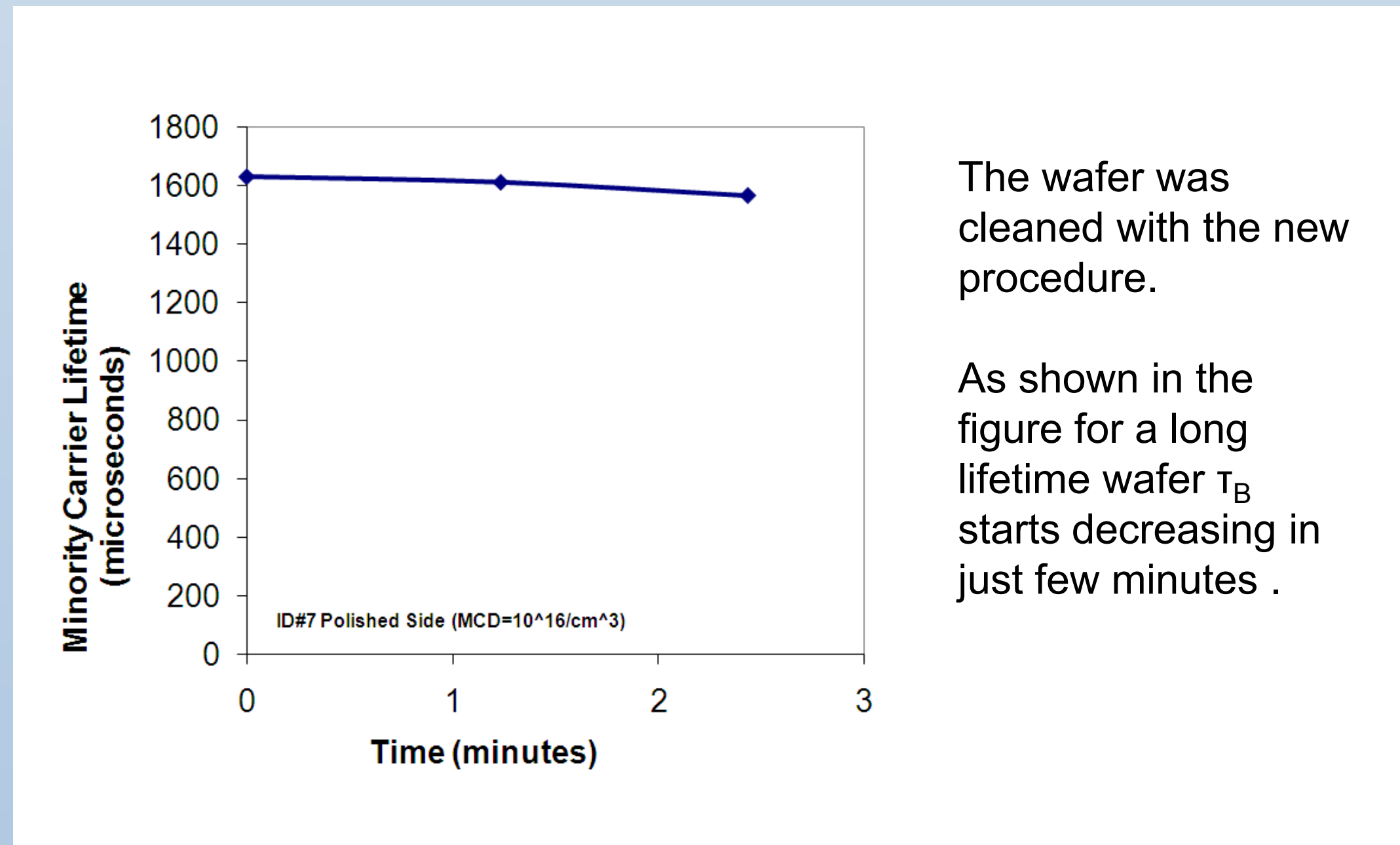
## LIGHT EXPOSURE EFFECT



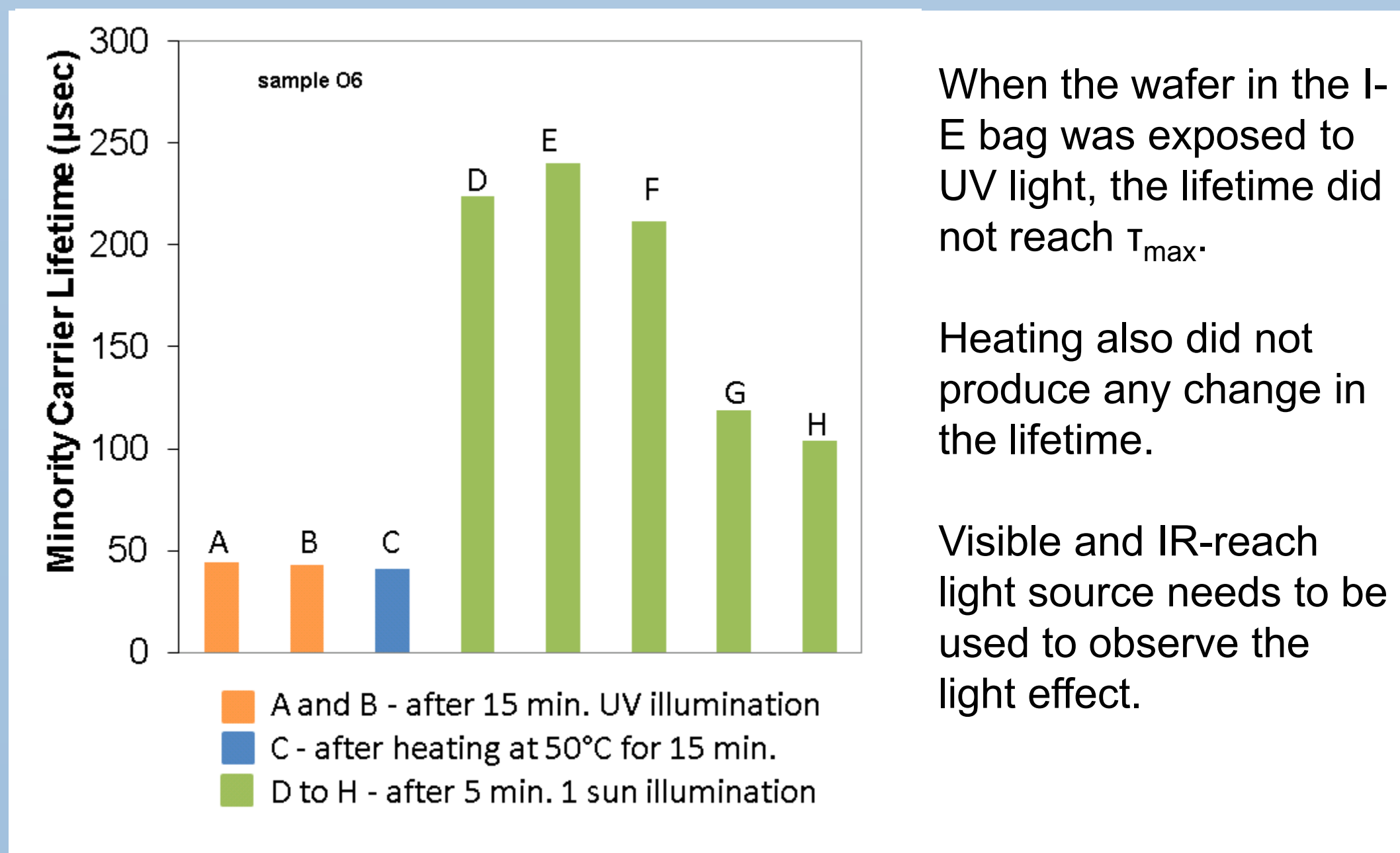
## TB DECAY AFTER LIGHT EXPOSURE



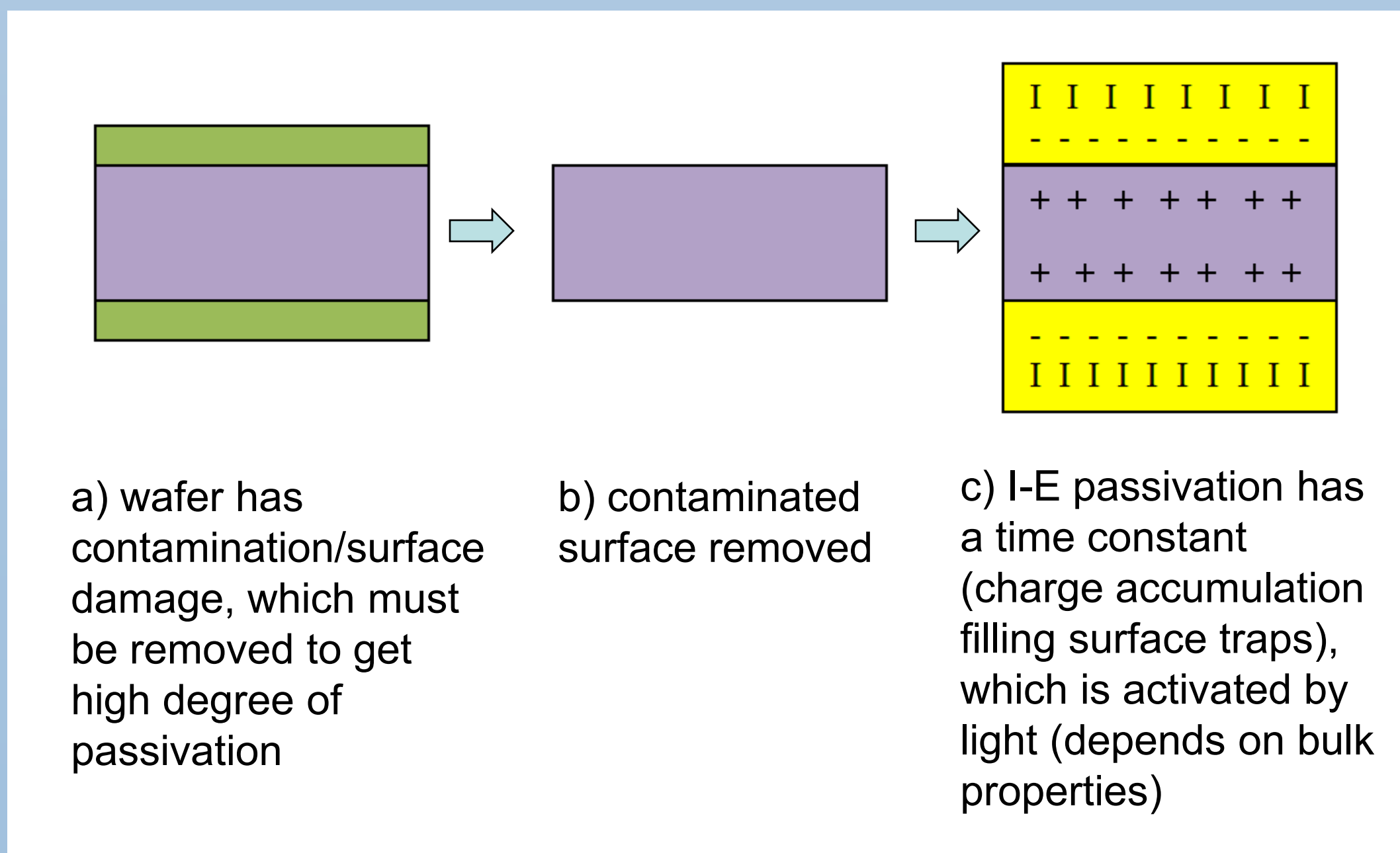
## VARIATION OF TB FOR A LONG LIFETIME WAFER



## WHAT IS BEHIND THE LIGHT EFFECT?



## SIMPLE MODEL FOR WAFER PREPARATION



## CONCLUSIONS

- Wafer cleaning procedure should include removal of about 200–300 Å of Si from each surface.
- We have outlined a procedure that yields a very clean surface.
- IE passivation may be sensitivity to light
- Unfortunately, our data on a variety of wafers are not consistent. For example, wafers from the same lot do not have the same dependence of lifetime on light exposure.